



SDM2A20CSP

2.0A SCHOTTKY BARRIER RECTIFIER CHIP SCALE PACKAGE

Low forward voltage (V_F) minimizes conduction losses and

Reduced high temperature reverse leakage; Increased reliability against thermal runaway failure in high temperature operation. Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2) Halogen and Antimony Free. "Green" Device (Note 3)

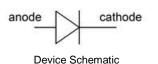
Product Summary

V _{RRM} (V)	I _O (A)	V _{F max} (V)	I _{R max} (μΑ)
20	2.0	0.53	80

Description and Applications

The SDM2A20CSP is a 20-volt 2A Schottky barrier rectifier that is optimized for low forward voltage drop and low leakage current. Housed in a compact chip scale package (CSP), the SDM2A20CSP occupies only 0.84 mm² board-space with low profile. The low thermal resistance enables designers to meet design challenges of increasing efficiency whilst at the same time reducing board space. It is ideally suited for use in portable applications as a:

- Blocking Diode
- Boost Diode
- Switching Diode
- Reverse Protection Diode



	Pin #1 Cathode Notch
Anode	Cathode

Features and Benefits

improves efficiency.

Mechanical Data

Case: X3-WLB1406-2

Polarity: Cathode Dot

Moisture Sensitivity: Level 1 per J-STD-020

Weight: 0.001 grams (Approximate)

Terminals: Solderable per MIL-STD-202, Method 208 (e4)

Ordering Information (Note 4)

Part Number	Case	Packaging
SDM2A20CSP-7	X3-WLB1406-2	5,000/Tape & Reel

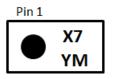
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead_free.htmlfor more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



X7=Product Type Marking Code YM=Date Code Marking Y=Year (ex: C=2015) M=Month (ex: 9=September) Dot Denotes Cathode Pin

Date Code	Key
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Notes:

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Year	201	4	2015		2016	20	17	2018		2019	2	2020
Code	В		С		D			F		G		Н
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	20	V
Average Rectified Output Current	lo	2.0	A
Repetitive Peak Forward Current (Pulse Wave = 1 Sec, Duty Cycle = 66%)	I _{FRM}	5.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	20	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	R _{0JA}	140	°C/W
Typical Thermal Resistance Junction to Ambient (Note 6)	R _{θJA}	73	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

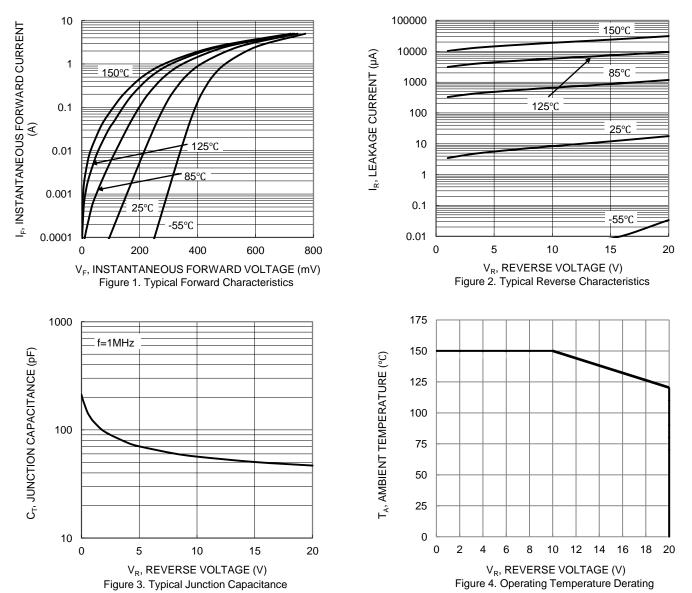
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
	N/		— 0.44	N	I _F = 1.0A	
Forward Voltage Drop	VF	—	-	0.53	v	I _F = 2.0A
Reverse Current (Note 7)		_	_	25		V _R = 10V
Reverse Current (Note 7)	IR		_	80	μA	V _R = 20V
Junction Capacitance	CT		70		pF	V _R = 5V, f = 1.0MHz

Notes: 5. Device mounted on FR-4 PCB, 2oz. Copper, minimum recommended pad layout per http://www.diodes.com/datasheets/ap02001.pdf. 6. Device mounted on FR-4 PCB, 2oz. 1 square inch Copper.

Device mounted on r r 4 r CB, 202. I square mon copper.
Short duration pulse test used to minimize self-heating effect.



SDM2A20CSP

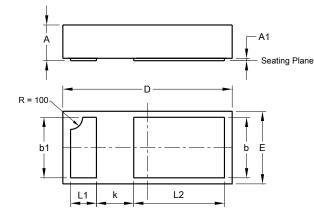


SDM2A20CSP Document number: DS37986 Rev. 3 - 2



Package Outline Dimensions

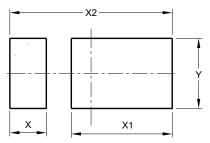
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X3-WLB1406-2						
Dim	Min	Max	Тур			
Α	0.250	0.300	0.275			
A1	0.000	0.015	-			
b	0.45	0.55	-			
b1	0.45	0.55	-			
D	1.37	1.43	1.40			
ш	0.57	0.63	0.60			
k	-	-	0.30			
L1	0.20	0.26	-			
L2	0.70	0.80	-			
All I	Dimens	ions in	mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Х	0.304
X1	0.840
X2	1.352
Ý	0.580



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